

Mouser is to stock all Linear products

Mouser is to stock Linear Technology products, including all power products from the newly-formed Power by Linear division.

“Design engineers around the world can now take advantage of this large, comprehensive portfolio of high performance signal chain, RF, and power management products from Analog Devices, including the entire Linear Technology product portfolio,” said Mouser’s Jeff Newell.

The distributor will stock the full breadth of Linear Technology products, including power management, data conversion, signal conditioning, RF and interface ICs, μ Modular subsystems, and wireless sensor network products.

The Power by Linear product line includes a wide range of power management products for industries including automotive, communication, industrial, and healthcare.

Tiny Bluetooth 4.2 module available from Solid State

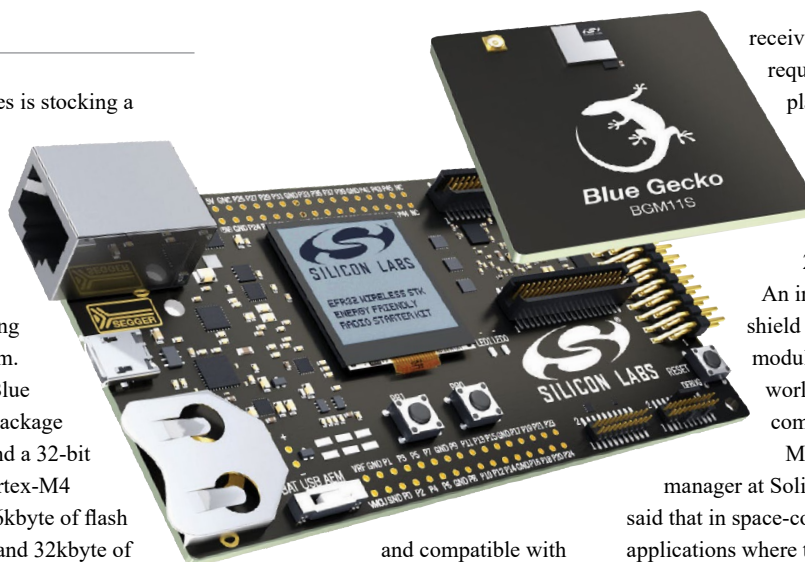
■ Solid State is to offer what Silicon Labs claims is the world’s ‘smallest’ system in package

RICHARD WILSON

Solid State Supplies is stocking a Bluetooth Low Energy (BLE) module from Silicon Labs which is one of the smallest available, measuring just 6.5x6.5x1.4mm.

The BGM11S Blue Gecko system in package (SiP) is built around a 32-bit 38.4MHz Arm Cortex-M4 processor with 256kbyte of flash program memory and 32kbyte of RAM data memory.

The device consumes 8.7mA when operating and 2.5 μ A in deep sleep mode. It is Bluetooth 4.2-compliant



and compatible with Bluetooth 5 advertising as well as being Bluetooth mesh-capable.

An integrated antenna offers up to +8dBm transmit power and -90dBm

receive sensitivity, requiring minimal PCB, plastic and metal clearance to deliver exceptional performance up to a range of 200m.

An inbuilt metal shield enables full modular certification for worldwide regulatory compliance.

Matt Cook, product manager at Solid State Supplies, said that in space-constrained applications where traditionally a chip design route would have been taken, “the BGM11S a compelling solution for the most demanding of applications”.

Charcroft tunes line-card for high-rel and COTS sectors

Charcroft Electronics has published a new line-card representing its specialisation in the design-in and sourcing of commercial, off-the-shelf (COTS), high-reliability and sector-approved components, writes Richard Wilson.

The products listed are likely to be most relevant for the avionics, high-end audio, defence, oil and gas, rail and space sectors. They cover passives, electromechanical, opto-electronics, RF and microwave components, as well as magnetics, power supplies, sensors and high-reliability semiconductors.

The company has also listed components that operate at the extremes of temperature, power, voltage, current and precision.

The distributor is also introducing a new marketing strapline: ‘Charcroft: Challenge Accepted’.

This was suggested by sales support staffer Beverley Turner, following a competition among the company’s employees to find a phrase that encapsulates its key differentiator in the market.

“The combination of the new line-card, with support from field-based product specialists and comprehensive quality documentation, will help engineers and buyers to simplify the design process from component selection to volume production,” said Charcroft Electronics’ company director, Debbie Rowland.

FOA and SEMI unite

After several years of close partnership, SEMI and the Fab Owners Association (FOA) have merged, writes David Manners.

Driving manufacturing efficiencies remains the overriding purpose of the FOA – where the A now stands for ‘Alliance’.

With the integration the FOA will leverage SEMI’s global infrastructure and connections to over 2,000 members around the world to extend its platforms for collaborative networking and benchmarking manufacturing operations.

“FOA members operate some of the most innovative and efficient fabrication facilities and are hotbeds for new optimisation methods in integrated circuit and micro-electromechanical production,”

said Ajit Manocha, president and CEO of SEMI. “The integration of FOA with SEMI brings together first-hand understanding of manufacturing challenges so we can help all SEMI members achieve higher operating efficiency.”

With integration complete, FOA (established in 2004) is managed as a special interest group (SIG) in SEMI. FOA member companies will become full SEMI members, with FOA continuing to expand its global membership through SEMI’s network, while maintaining its unique community.

SEMI-FOA will continue to focus on manufacturing efficiency, including the group’s benchmark activities, to enable best practices among FOA members.